



Patent

Customer No.: 31561
Docket No.: 10546-US-PA
Application No.: 10/709,953

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Huang et al.
Application No. : 10/709,953
Filed : 2004/6/9
For : CHIP PACKAGING STRUCTURE HAVING
REDISTRIBUTION LAYER WITH RECESS
Art Unit : 2826
Examiner : Williams, Alexander O.

TRANSMITTAL LETTER

+1-571-273-2885

(Via fax: 1+2 pages)

Assistant Commissioner for Patents
Alexandria, VA 22314

Dear Sir,

In response to the Notice of Allowance and Fee(s) due, dated April 4, 2007 transmitted herewith please find the Issue Fee Transmittal (PTOL-85B) in duplicate.

Please charge the fee in the amount of \$1700.00 for Issue Fee and Publication Fee to Account No. 50-2620 (Order No.: 10546-US-PA).

Please be kindly advised that the title of the invention has been amended to "CHIP PACKAGING STRUCTURE HAVING REDISTRIBUTION LAYER WITH RECESS" in the amendment and response to office action, dated November 1, 2006.

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,
JIANQ CHYUN Intellectual Property Office

Date: June 27, 2007

By: Belinda Lee
Belinda Lee
Registration No.: 46,863

Please send future correspondence to:

7F. -1, No. 100, Roosevelt Rd.,

Sec. 2, Taipei 100, Taiwan, R.O.C.

Tel: 886-2-2369 2800

Fax: 886-2-2369 7233 / 886-2-2369 7234

E-MAIL: BELINDA@JCIPGroup.com.tw; USA@JCIPGroup.com.tw